



Light Beam Soldering Equipment LP-8150MKII

Because of a comprehensive model change, functions and operability of this model have been greatly improved.

By using the quartz rod lens (sold separately) soldering within a small part has become possible.

Features

- * Near-infrared rays emitted by the 150W halogen lamp are collected by the reflecting mirror, which concentrates some 850°C of heat at the focal point (a spot with a diameter of about 5mm).
- * No heating takes place outside the focal point. Because the light beam produces non-contact heating, it can be described as "clean heat".
- * Immediately on switching ON, within about 1 second soldering can be done within an area of 5mm diameter in the case of a printed circuit board (using cream solder on chip parts).
- * With the 4mm diameter quartz rod lens (sold separately), soldering can also be carried out inside small (5mm diameter) plastic bobbins (heat at point directly under the lens 450°C).
- * Luminescence (heat) output can be adjusted from 10% to 100% of full power.
- * Lamp box is freely adjustable in the up-down, forward-backward directions, and can be easily installed on a robot arm, etc.

Specifications

- Light (heat) source : Halogen lamp 15V 150W (with mirror)
- Focal point : Focal distance : 32mm
Focal diameter : 5mm
Temperature : About 850°C
(calibrated with thermocouple)
- Light(heat) output : 150W (100 to 850°C)
adjustable 10% to 100%
- Irradiation time : When switch is in ON position during
NORMAL : START switch or REMOTE
SWITCHING operation
TIMER : 0.1 to 10 seconds interval
(1 to 100 seconds with changeover)
- Output control : Wave form phase controlled by thyristor
- Remote switch : A contact or transistor switch 5V 30mA.
- Power supply : AC100V/120V/220V/240V 150W 50/60Hz
- External dimensions : (W)230×(D)200×(H)300mm
- Weight : about 6.5kg

Applications

- Soldering of chips for hybrid IC or SMT board, SOP-IC, LSI (using cream solder).
- Dismounting of chip parts, SOP-ICs (8 to 16 pin) (using mask).
- Removal of the mold from plastic mold ICs, LSI molds (using fuming nitric acid, the chip is perfectly exposed in about 10 minutes).

Options

- Rod lens (with lens holder)
Quartz glass 3.8ø×48mm,
step mode, efficiency=50%
- Halogen lamp
(changeable, with mirror)
- Hot mask

* Specifications subject to change without notice.